

# Precision Adjustable Current Limited Power Distribution Switches

## 1 FEATURES

- **Typical 27µA Low Quiescent Current**
- **Typical 0.1µA Shutdown Current**
- **No Reverse Input-Output Leakage Current**
- **Meets USB Current Limiting Requirements**
- **Adjustable Current Limit: 400mA to 2.7A**
- **Fast Over-Current Response**
- **70mΩ High-side MOSFET**
- **Under Voltage Lockout**
- **Thermal Shutdown Protection**
- **Operating Range: 2.5V to 5.5V**
- **Built-In Soft-Start Function**
- **Available in the Green SOT23-6 Package**

## 2 APPLICATIONS

- **USB Host and Self-Powered Hubs**
- **USB Bus-Powered Hubs**
- **USB Power Management**
- **General Purpose Power Switch (High Side)**
- **Hot Plug-in Power Supplies**
- **Battery-Charger Circuits**

## 3 DESCRIPTION

The RS2583 is an integrated power switch for self-powered and bus-powered Universal Serial Bus (USB) applications.

The RS2583 is a cost-effective, low voltage, single P-channel MOSFET load switch with 70mΩ RDS(ON), which is free of parasitic body diode and has no reverse input-output leakage current. When the output voltage is higher than input voltage, the power switch is turned off by internal output reverse-voltage protector.

Several protection features include current limiting and thermal shutdown to prevent catastrophic switch failure caused by increasing power dissipation when continuous heavy loads or short circuit occurs.

FLAG is an open-drain output report over-current or over-temperature event and has typical 13ms deglitch timeout period. In addition, FLAG also reports output reverse-voltage condition with typical 5ms deglitch timeout period.

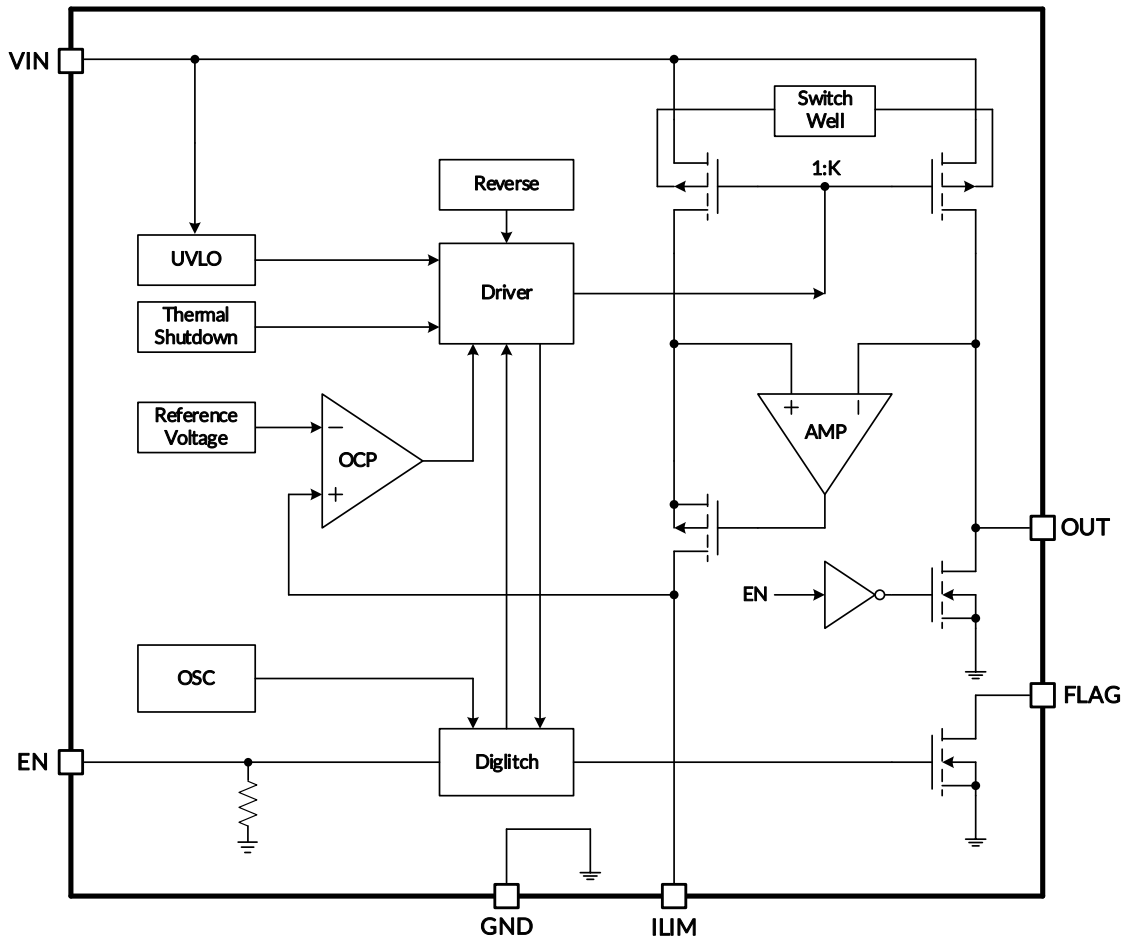
RS2583 is available in the Green SOT23-6 package. It is rated over the -40°C to +85°C temperature range.

### Device Information <sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
RS2583	SOT23-6(6)	2.90mm×1.60mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

**4 FUNCTIONAL BLOCK DIAGRAM**



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## 5 REVISION HISTORY

Note: Page numbers for previous revisions may differ from page numbers in the current version.

VERSION	Change Date	Change Item
A.1	2023/08/18	Initial version completed

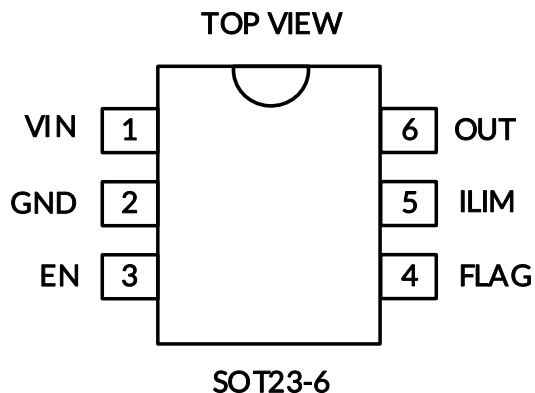
**6 PACKAGE/ORDERING INFORMATION <sup>(1)</sup>**

PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING <sup>(2)</sup>	PACKAGE OPTION
RS2583	RS2583YH6	-40°C ~+85°C	SOT23-6	2583	Tape and Reel,3000

## NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information(data code and vendor code), the logo or the environmental category on the device.

## 7 PIN CONFIGURATIONS



### PIN DESCRIPTION

PIN	NAME	DESCRIPTION
<b>SOT23-6</b>		
1	VIN	Power Supply Input. The P-Channel Source of Switch, Which also supplies IC's internal circuitry. Connect to Positive Supply.
2	GND	Ground.
4	EN	Enable Input. Logic Level Enable Input, Active high available. Internal pulldown.
4	FLAG	Fault Flag. Active low, open-drain output. Indicates over-current or thermal shutdown conditions. Over-current condition must last longer than $t_d$ in order to assert FLAG
5	ILIM	Current limit set pin. Connect a resistor between this pin and ground to program the desired current limit set point. Do Not Float this PIN.
6	OUT	Switch Output. The P-Channel Drain of Switch, Which Typically Connects to Load.

## 8 SPECIFICATIONS

### 8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>IN</sub>	Supply voltage range	-0.3	6.0	V
V <sub>OUT</sub>	Output voltage range	-0.3	6.0	V
V <sub>EN</sub>	EN Input Voltage	-0.3	6.0	V
V <sub>ILIM</sub>	ILIM Output Voltage	-0.3	6.0	V
V <sub>FLAG</sub>	FLAG Output Voltage	-0.3	6.0	V
P <sub>D</sub>	Power Dissipation		0.3	W
θ <sub>JA</sub>	Package thermal impedance <sup>(2)</sup>	SOT23-6		200 °C/W
T <sub>J</sub>	Junction temperature <sup>(3)</sup>	-40	150	°C
T <sub>stg</sub>	Storage temperature	-65	150	°C
T <sub>L</sub>	Lead Temperature (Soldering,10secs)		260	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The package thermal impedance is calculated in accordance with JESD-51.

(3) The maximum power dissipation is a function of T<sub>J(MAX)</sub>, R<sub>θJA</sub>, and T<sub>A</sub>. The maximum allowable power dissipation at any ambient temperature is P<sub>D</sub> = (T<sub>J(MAX)</sub> - T<sub>A</sub>) / R<sub>θJA</sub>. All numbers apply for packages soldered directly onto a PCB.

### 8.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

		VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	Human-body model (HBM), MIL-STD-883K METHOD 3015.9	±4000	V
	Charged-device model (CDM), ANSI/ESDA/JEDEC JS-002-2018	±1500	



#### ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.3 Recommended Operating Rating

		MIN	MAX	UNIT
V <sub>IN</sub>	Supply voltage range	2.5	5.5	V
V <sub>OUT</sub>	Output voltage range	0	5.5	V
V <sub>EN</sub>	EN Input Voltage	0	5.5	V
V <sub>ILIM</sub>	ILIM Output Voltage	0	5.5	V
I <sub>ILIM</sub>	Output Current Limit	0.4	2.7	A
T <sub>J</sub>	Junction temperature	-40	125	°C
T <sub>A</sub>	Operating Temperature	-40	85	°C

## 8.4 ELECTRICAL CHARACTERISTICS

( $V_{IN}=5.0V$ ,  $T_A = +25^{\circ}C$ , unless otherwise noted.) <sup>(1)</sup>

PARAMETER	SYMBOL	TEST CONDITIONS	MIN <sup>(2)</sup>	TYP <sup>(3)</sup>	MAX <sup>(2)</sup>	UNIT
Power Input Voltage Range	$V_{IN}$		2.5		5.5	V
Power Supply Current	$I_Q$	Switch on, $V_{OUT}=\text{Open}$		27	50	$\mu A$
Shutdown Supply Current	$I_{SD}$	Switch off, $V_{OUT}=\text{Open}$		0.1	1.0	$\mu A$
Under-Voltage Lockout Threshold	$V_{UVLO}$	$C_{IN}=10\mu F$		1.9	2.4	V
Under-Voltage Lockout Threshold Hysteresis	$V_{UVLO\_HY}$	$C_{IN}=10\mu F$		0.1	0.2	V
Switch Resistance	$R_{DS(ON)}$	$I_{OUT}=500mA$		70	80	$m\Omega$
Enable Input Threshold	$V_{IH}$	$V_{IN}=2.5V$ to $5.5V$ , $C_{IN}=10\mu F$	1.6			V
	$V_{IL}$	$V_{IN}=2.5V$ to $5.5V$ , $C_{IN}=10\mu F$			0.4	V
Enable Pull Down Resistance	$R_{EN}$	$V_{IN}=2.5V$ to $5.5V$		500		$k\Omega$
Output Turn-On Delay Time	$t_{ON}$	$C_{IN}=10\mu F$ , $R_L=10\Omega$ , $C_L=1\mu F$		2.0	3.0	ms
Output Turn-Off Delay Time	$t_{OFF}$	$C_{IN}=10\mu F$ , $R_L=10\Omega$ , $C_L=1\mu F$		20	50	$\mu s$
Response Time to Short Circuit	$t_{SCR}$	$C_{IN}=470\mu F$ to $1000\mu F$		6.0		$\mu s$
Current Limit Threshold	$I_{LIMIT}$	$C_{IN}=10\mu F$ , $C_L=1\mu F$ , $R_{LIM}=27K$	0.44	0.5	0.56	A
Short-Circuit Current Threshold	$I_{SHORT}$	$C_{IN}=10\mu F$ , $C_L=1\mu F$ , $R_{LIM}=27K$		0.375		A
Over-Current FLAG Response Delay Time	$t_D$	$C_{IN}=10\mu F$ , $C_L=1\mu F$ , $V_{OUT}=0$ until FLAG is low		13	20	ms
FLAG Output Low Voltage	$V_{FLAG\_L}$	$C_{IN}=10\mu F$ , $I_{SINK}=2mA$			0.4	V
FLAG Output Leakage Current	$I_{FLAG\_L}$	$C_{IN}=10\mu F$ , $V_{OC}=5V$		0.1	1	$\mu A$
OUT Shutdown Discharge Resistance	$R_{DIS}$	$C_{IN}=10\mu F$ , Switch off		270	350	$\Omega$
Thermal Shutdown Temperature	$T_{SD}$	$C_{IN}=10\mu F$		145		$^{\circ}C$
Thermal Shutdown Hysteresis	$T_{SD\_HY}$	$C_{IN}=10\mu F$		20		$^{\circ}C$

(1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.

(2) Limits are 100% production tested at  $25^{\circ}C$ . Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.



### 8.5 PARAMETER MEASUREMENT INFORMATION

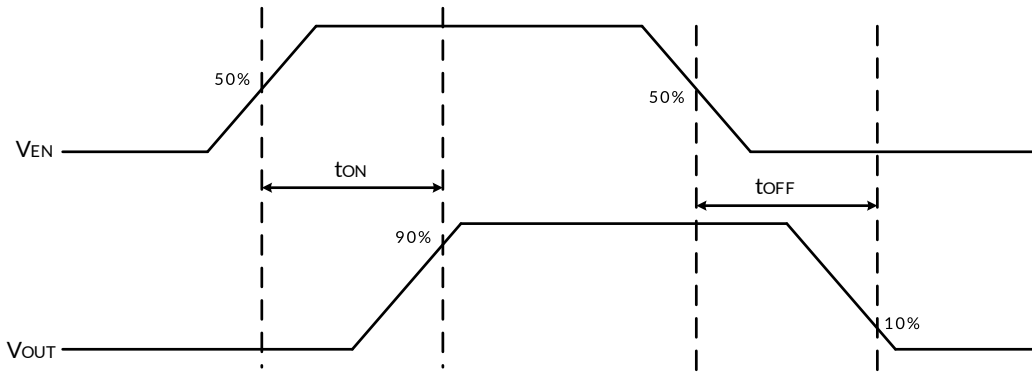


Figure 1. Switch Turn-On and Turn-Off Delay Time

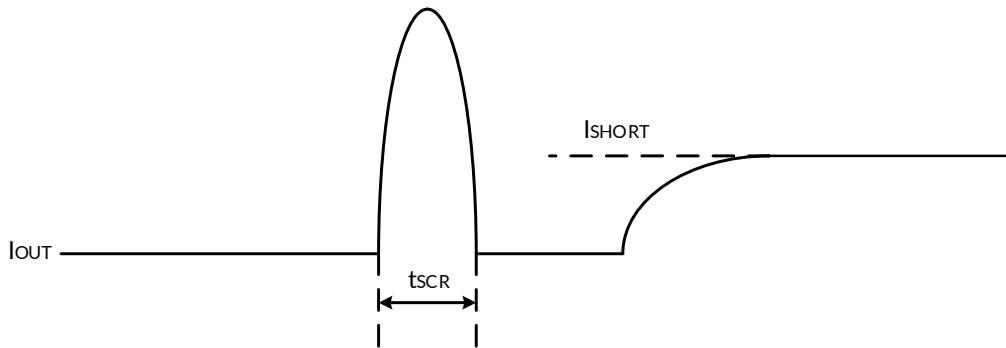


Figure 2. Short-Circuit Response Time

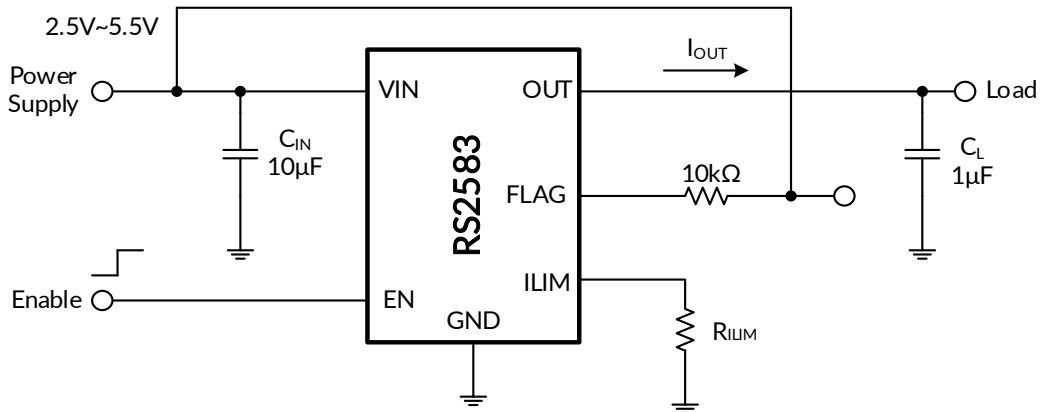


Figure 3. Typical Application Circuit

## 8.6 TYPICAL PERFORMANCE CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

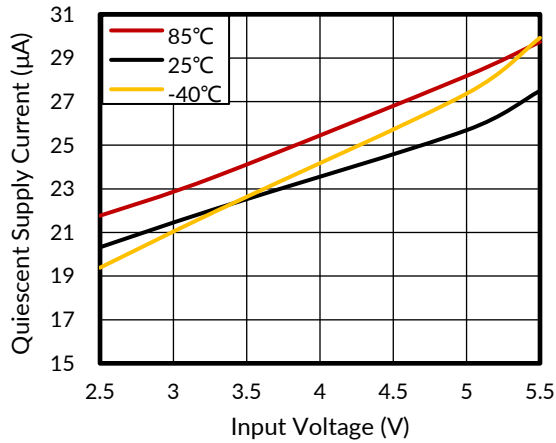


Figure 4. Quiescent Current vs Input Voltage

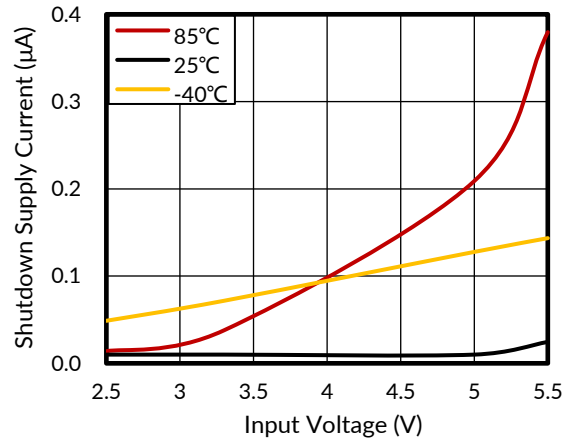


Figure 5. Shutdown Current vs Input Voltage

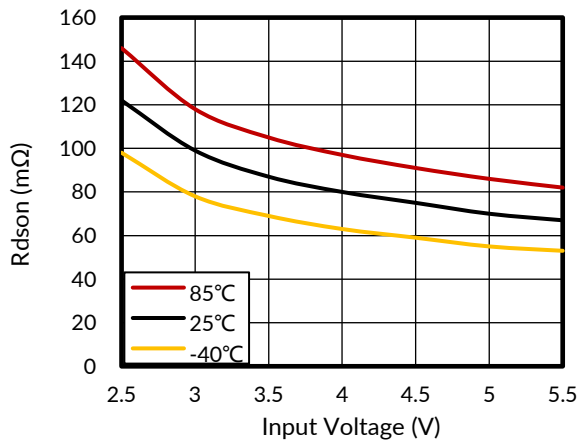


Figure 6. High-side MOSFET On Resistance vs Input Voltage

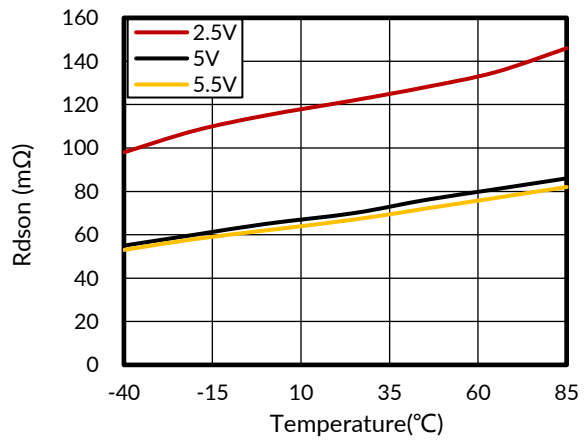


Figure 7. High-side MOSFET On Resistance vs Temperature

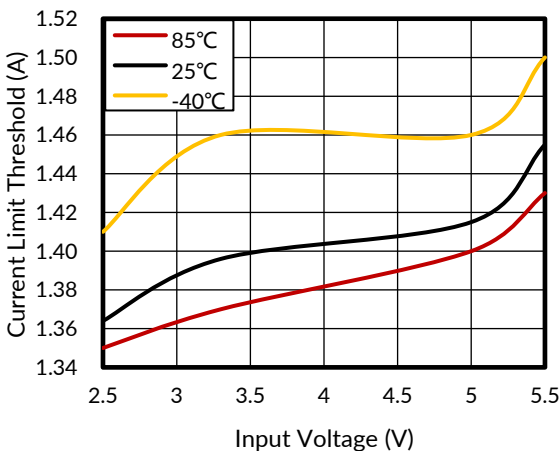


Figure 8. Current Limit Threshold vs Input Voltage

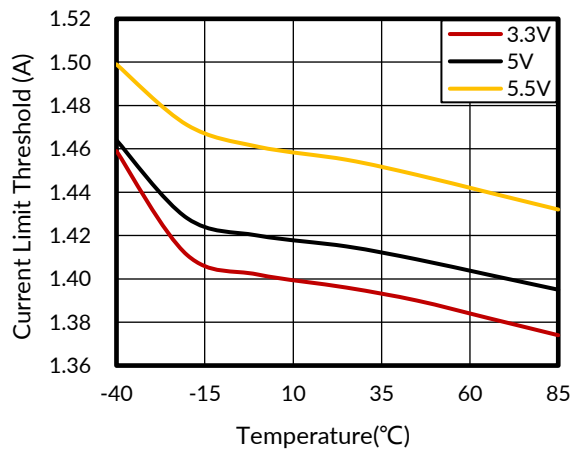
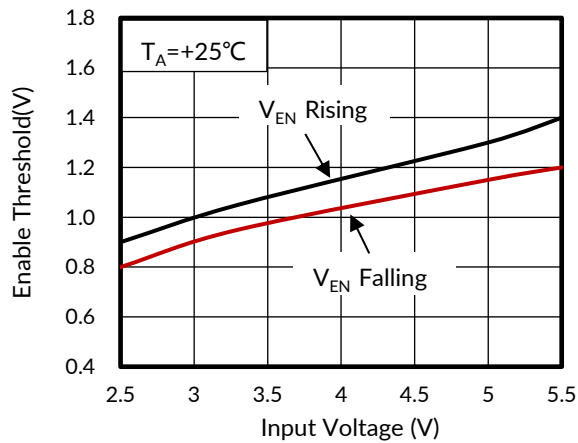


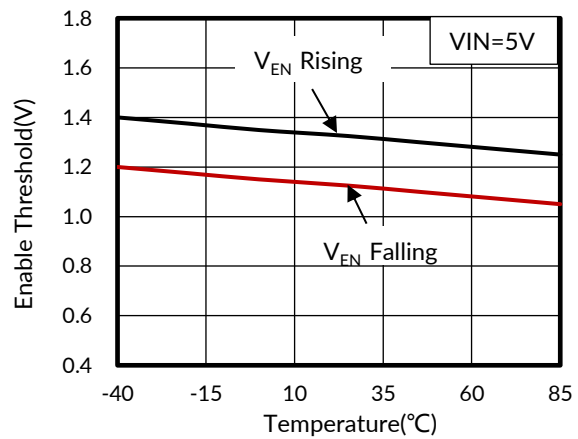
Figure 9. Current Limit Threshold vs Temperature

## TYPICAL PERFORMANCE CHARACTERISTICS

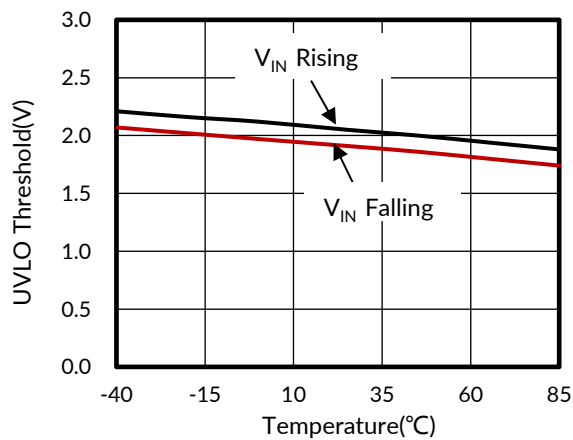
NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.



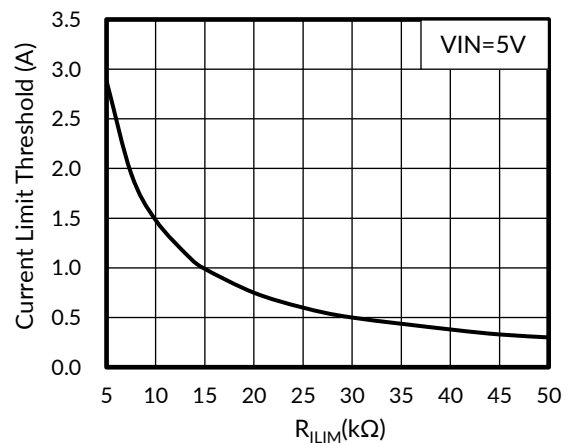
**Figure 10. Enable Threshold vs Input Voltage**



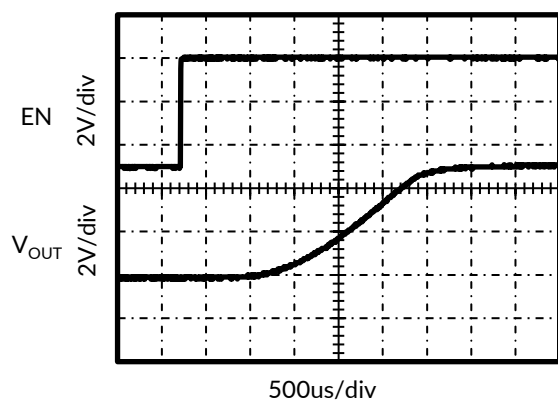
**Figure 11. Enable Threshold vs Temperature**



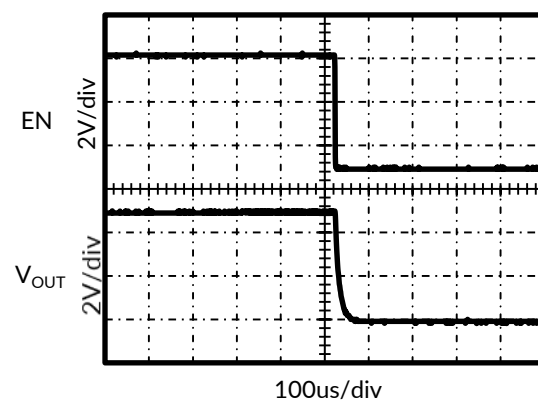
**Figure 12. UVLO Threshold vs Temperature**



**Figure 13. Current Limit Threshold vs  $R_{ILIM}$**



**Figure 14. Turn-On Delay Time**



**Figure 15. Turn-Off Delay Time**

## TYPICAL PERFORMANCE CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

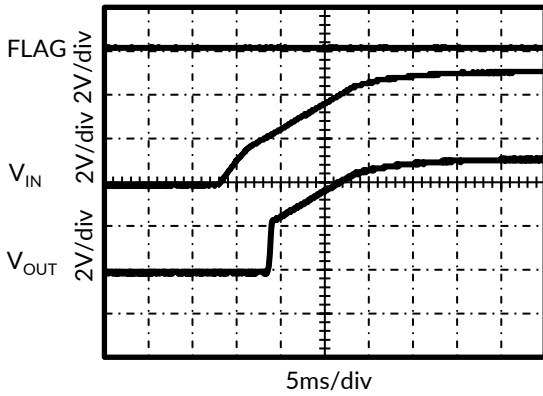


Figure 16. UVLO at  $V_{IN}$  Rising

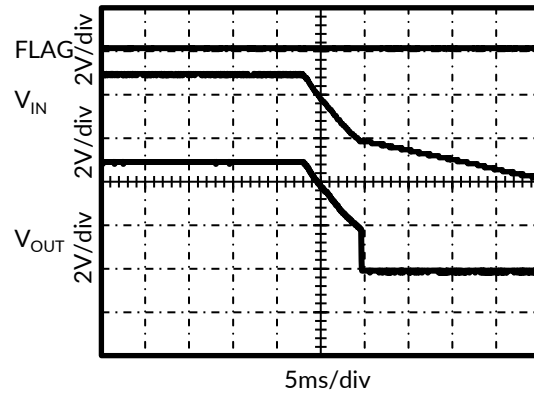


Figure 17. UVLO at  $V_{IN}$  Falling

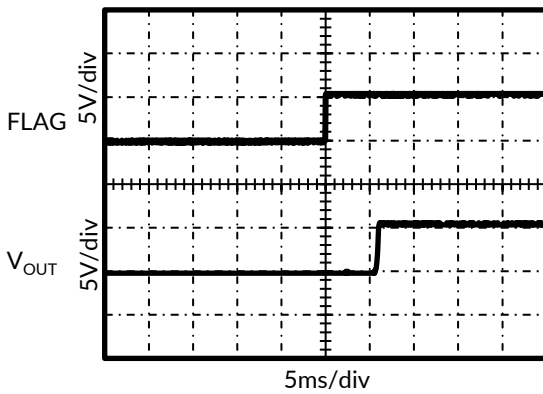


Figure 18. Exit Over Temperature Protection

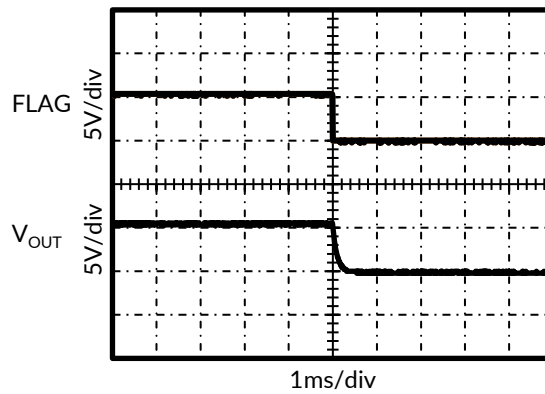


Figure 19. Enter Over Temperature Protection

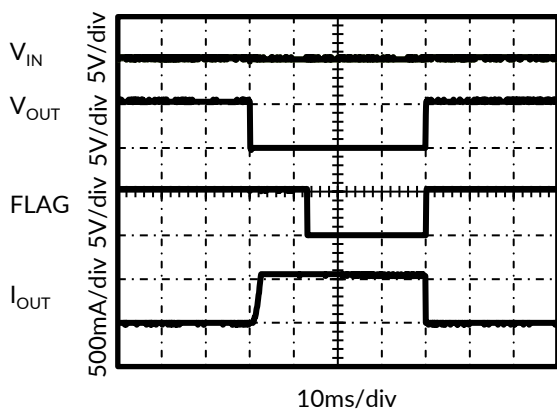


Figure 20. No Load into Short-Circuit

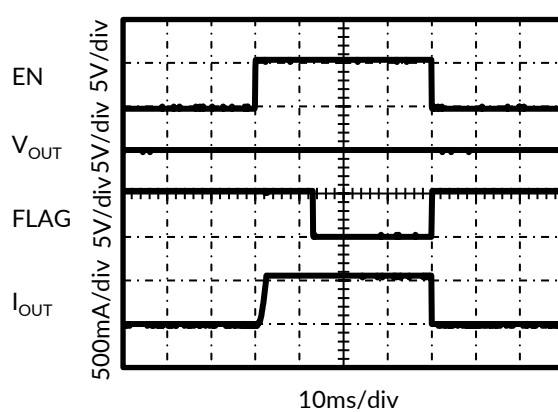
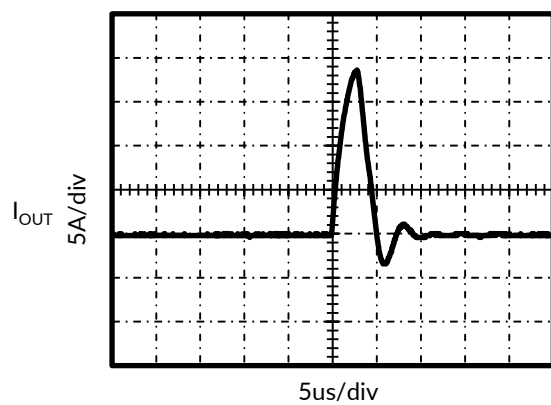


Figure 21. Device Enabled into Short-Circuit

## TYPICAL PERFORMANCE CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.



**Figure 22. Short-Circuit Response Time**

## 9 DETAILED DESCRIPTION

### 9.1 Input and Output

VIN is the power supply connection to the logic circuitry and the source of the P-channel MOSFET. OUT is the drain of the P-channel MOSFET. In a typical circuit, current flows from VIN to OUT toward the load. The output P-channel MOSFET and driver circuit are also designed to allow the MOSFET drain to be externally forced to a higher voltage than the source ( $V_{OUT} > V_{IN}$ ) when the switch is disabled.

### 9.2 Thermal Shutdown

Thermal shutdown is employed to protect device and load from damage because of excessive power dissipation. It shuts off the output MOSFET and asserts the FLAG output, if the die temperature exceeds 145°C until the die temperature drops to 125°C.

### 9.3 Soft-Start

In order to eliminate the upstream voltage sag caused by the large inrush current during hot-plug events, the soft-start feature effectively isolates power supplies from such highly capacitive loads.

### 9.4 Under-Voltage Lockout (UVLO)

UVLO prevents the MOSFET switch from turning on until input voltage exceeds 1.9V (Typical). If input voltage drops below 1.8V (Typical), UVLO shuts off the MOSFET switch. Under-voltage detection functions only when the switch is enabled.

### 9.5 Current Limiting and Short-Circuit Protection

The current limit circuit is designed to limit the output current to protect the upstream power supply. Current limit threshold is programmed with a resistor from ILIM to ground marked as  $R_{ILIM}$ . It can be estimated by the following equation:

$$I_{LIM} \approx \frac{13500}{R_{ILIM}}, I_{SHORT} \approx 0.75 * \frac{13500}{R_{ILIM}}$$

We recommend the  $R_{ILIM}$  value range: 5KOhm~36KOhm. For more details, please refer to Figure 13.

Under output short-circuit condition; the typical current limit folded back 75%. If the RS2583 keeps at over-current condition for a long time, the junction temperature may exceed 145°C, and over-temperature protection will shut down the output until temperature drops 125°C or limit (short-circuit) condition is removed.

**Table 1. Typical Design Examples**

ILIM(A)	$R_{ILIM}(k\Omega)$
0.5	29.4
1	14.5
1.5	9.42
2	7.06
2.7	5.17

### 9.6 Reverse-Voltage Protection

The reverse-voltage protection feature turns off the P-MOSFET switch whenever the output voltage exceeds the input voltage by 50mV.

### 9.7 Fault Flag (FLAG)

The signal is an open-drain N-MOSFET output. FLAG is asserted (active low) when an over-current, short-circuit or thermal shutdown condition occurs.

In the case of an over-current condition, FLAG will be asserted only after the response delay time ( $t_D$ ) has elapsed. This ensures that FLAG is asserted only upon valid over-current condition and that erroneous error reporting is

eliminated.

False over-current condition can occur during hot-plug events when a highly capacitive load is connected and causes a high transient inrush current that exceeds the current limit threshold for up to 1ms. The FLAG response delay time  $t_D$  is 13ms (Typical).

## 9.8 Power Dissipation

The device's junction temperature depends on several factors such as the load, PCB layout, ambient temperature, and package type. Equations that can be used to calculate power dissipation and junction temperature are found below:

$$P_D = R_{DS(ON)} \times I_{OUT}^2$$

To relate this to junction temperature, the following equation can be used:

$$T_J = P_D \times \theta_{JA} + T_A$$

Where:

$T_J$  = junction temperature

$T_A$  = ambient temperature

$\theta_{JA}$  = the thermal resistance of the package

## 9.9 Supply Filter Capacitor

In order to prevent the input voltage drooping during hot-plug events, connect a ceramic capacitor ( $C_{IN}$ ) from VIN to GND. The  $C_{IN}$  is positioned close to VIN and GND of the device. However, higher capacitor values could reduce the voltage sag on the input further. Furthermore, an output short will cause ringing on the input without the input capacitor. It could destroy the internal circuitry when the input transient exceeds 6.0V which is the absolute maximum supply voltage even for a short duration.

If the upstream supply cable is long or the VIN transient exceeds 6.0V during the  $V_{OUT}$  short, recommend adding a second filter capacitor at the upstream supply output terminal.

## 9.10 Output Filter Capacitor

A low-ESR 10uF ceramic capacitor between OUT and GND is strongly recommended to reduce the voltage droop during hot-attachment of downstream peripheral. Higher value output capacitor is better when the output load is heavy. Additionally, bypassing the output with a 0.1uF ceramic capacitor improves the immunity of the device to short-circuit transients.

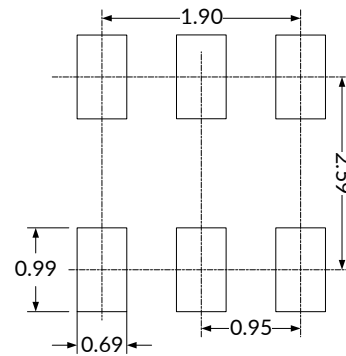
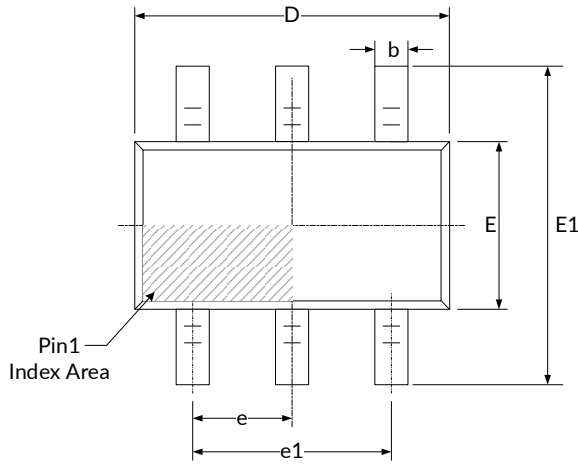
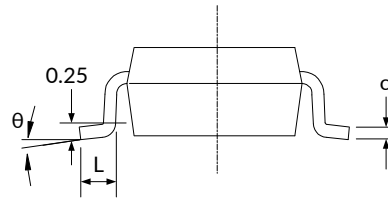
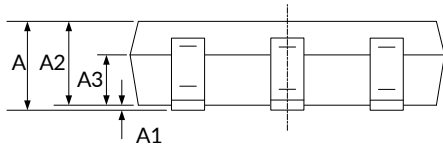
## 9.11 PCB Layout Guide

For best performance of the RS2583, the following guidelines must be strictly followed:

1. Please place the input capacitors near the VIN pin as close as possible.
2. Keep VIN and OUT traces as wide and short as possible.
3. Locate RS2583 and output capacitors near the load to reduce parasitic resistance and inductance for excellent load transient performance.
4. Input and output capacitors should be placed closed to the IC and connected to ground plane to reduce noise coupling. Place a ground plane under all circuitry to lower both resistance and inductance and improve DC and transient performance
5. The traces routing the  $R_{ILIM}$  resistor to the RS2583 should be as short as possible to reduce parasitic effects on the current limit accuracy.

# 10 PACKAGE OUTLINE DIMENSIONS

## SOT23-6 <sup>(2)</sup>


**RECOMMENDED LAND PATTERN (Unit: mm)**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A <sup>(1)</sup>		1.250		0.049
A1	0.020	0.110	0.001	0.004
A2	1.000	1.200	0.039	0.047
A3	0.600	0.700	0.024	0.028
b	0.330	0.410	0.013	0.016
c	0.150	0.190	0.006	0.007
D <sup>(1)</sup>	2.800	3.000	0.110	0.118
E <sup>(1)</sup>	1.500	1.700	0.059	0.067
E1	2.600	3.000	0.102	0.118
e	0.850	1.050	0.033	0.041
e1	1.800	2.000	0.071	0.079
L	0.350	0.550	0.014	0.022
θ	0°	8°	0°	8°

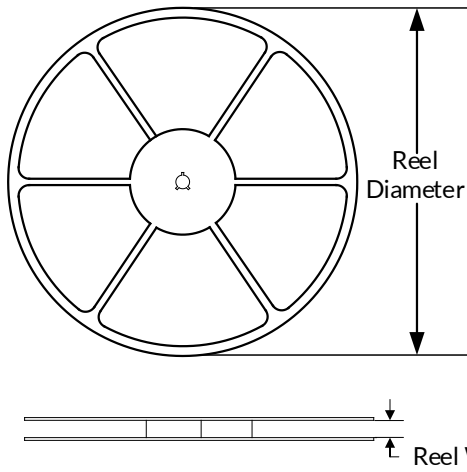
**NOTE:**

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. This drawing is subject to change without notice.

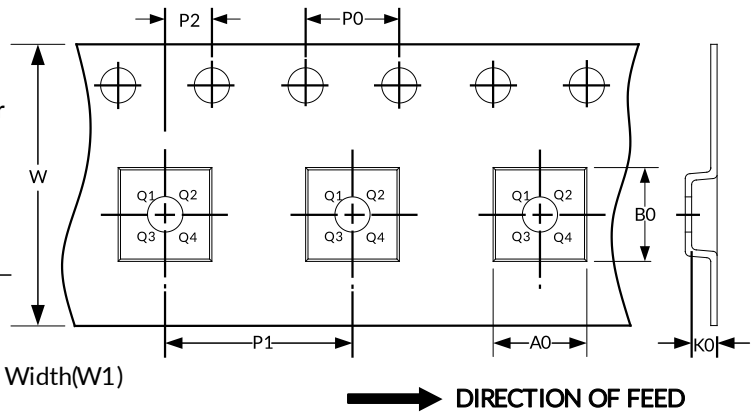


# 11 TAPE AND REEL INFORMATION

## REEL DIMENSIONS



## TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-6	7"	9.5	3.17	3.23	1.37	4.0	4.0	2.0	8.0	Q3

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

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